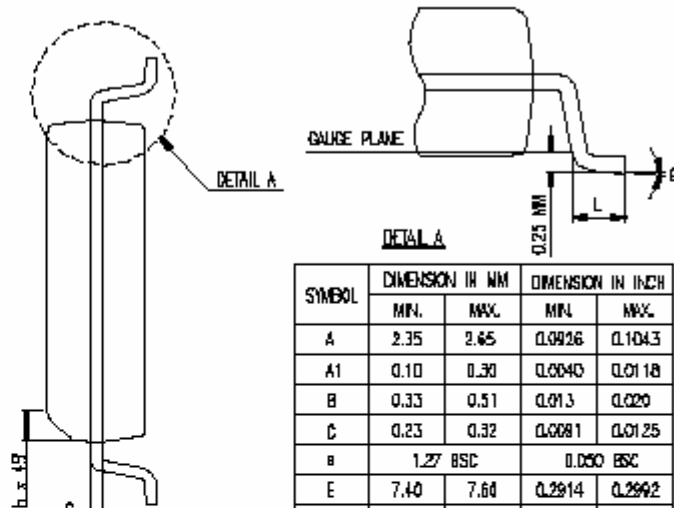
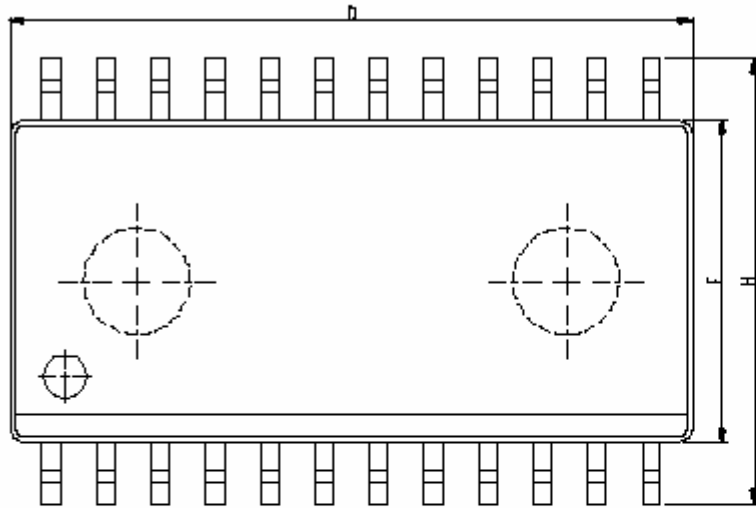


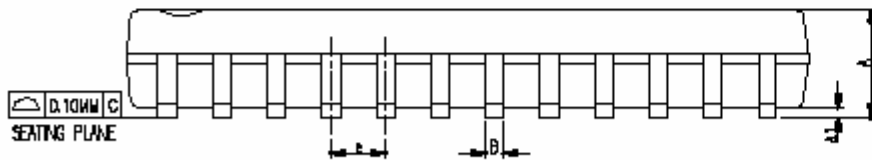
# TM58P20 28 PIN DIP 300mil(Device Package)

REV.	DESCRIPTION	BY	DATE
ORC.	DRAWING ISSUE	SANDY CHEN	01.16.98
A.	ADD NOTES	SANDY CHEN	01.20.00



**DETAIL A**

SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN.	MAX.	MIN.	MAX.
A	2.35	2.65	0.0926	0.1043
A1	0.10	0.30	0.0040	0.0118
B	0.33	0.51	0.013	0.020
C	0.23	0.32	0.0091	0.0125
a	1.27 BSC		0.050 BSC	
E	7.40	7.60	0.2914	0.2992
H	10.00	10.65	0.394	0.419
L	0.40	1.27	0.016	0.050
h	0.25	0.75	0.010	0.029
Ø	Ø	Ø	Ø	Ø



H	D DIMENSION (IN MM)		D DIMENSION (IN INCH)		JEDEC
	MIN.	MAX.	MIN.	MAX.	
20	12.60	13.00	0.4961	0.5118	WS-013 (AC)
24	15.20	15.60	0.5985	0.6141	WS-013 (AD)
28	17.70	18.10	0.6969	0.7125	WS-013 (AE)

⚠️ NOTES : DIMENSION " D " DOES NOT INCLUDE MOLD FLASH , PROTRUSIONS OR GATE BURRS. MOLD FLASH , PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 0.13 MM ( 0.008 INCH ) PER SIDE.

# TM58P20 28 PIN DIP 600mil(Device Package)

